

PSE Technology Corporation

SPECIFICATION FOR APPROVAL

CUSTOMER _____

NOMINAL FREQUENCY 24.000000 MHz




PRODUCT TYPE TYPE F9 5.0x3.2 GLASS SEALED CRYSTAL

SPEC. NO. (P/N) F92400054

CUSTOMER P/N _____

ISSUE DATE August 23, 2013

VERSION C

APPROVED	PREPARED	QA
		
APPROVED BY CUSTOMER :		AVL Status
Please return one copy with approval to PSE-TW		

PSE Technology Corporation

No.2, Tzu-Chiang 5th Rd, Chung Li Industrial Park,
 Chung Li City, Taoyuan County, Taiwan (R.O.C.)
 TEL: 886-3-451-8888
 FAX: 886-3-461-3865
<http://www.saronix-ecera.com.tw>

*RoHS Exemption
 *HF-Halogen Free
 *REACH Compliant

*** A company of  PERICOM Semiconductor Corporation ***

TYPE F9 5.0x3.2 GLASS SEALED CRYSTAL

F92400054

VER. C 23-Aug-13

ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	24.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	18	pF	
Calibration Tolerance	FL	±30	ppm	at 25°C±3°C
Operating Temperature Range	TR	-20 to +70	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±30	ppm	Reference to the Frequency at 25° C
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	60	Ω	Max
Shunt Capacitance	C0	5	pF	Max.
Aging at 25°C		±5	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	MΩ	Min

TYPE F9 5.0x3.2 GLASS SEALED CRYSTAL

F92400054

VER. C 23-Aug-13

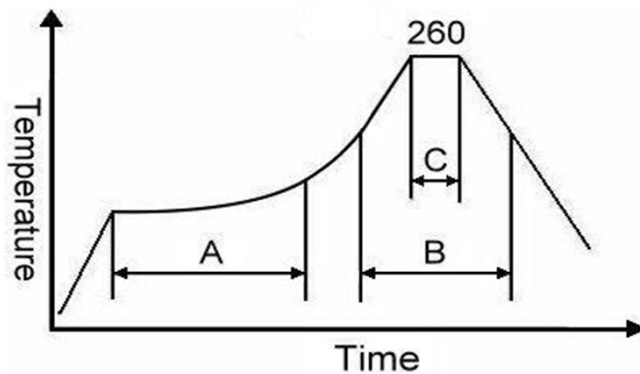
RELIABILITY SPECIFICATIONS

MECHANICAL AND ENVIRONMENTAL RATINGS:

- a) FINE LEAK TEST: JESD22-A109 (Condition 1A)
- b) GROSS LEAK TEST: JESD22-A109 (Condition C)
- c) MOISTURE RESISTANCE: JESD22-A113
- d) SHOCK: JESD22-B104 (Condition B)
- e) SOLDERABILITY : (RoHS version): J-STD-002
- f) VIBRATION: JESD22-B103
- g) SOLVENT RESISTANCE: JESD22-B107
- h) RESISTANCE TO SOLDERING HEAT (RoHS version): J-STD-020D Table 5.2 Pb free devices (3 cycles max)

SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D



Note:

	Stage	Temperature	Time
A	Preheat	150~200°C	60~120 Sec
B	Primary Heat	217°C	60~150 Sec
C	Peak	260°C	10 Sec

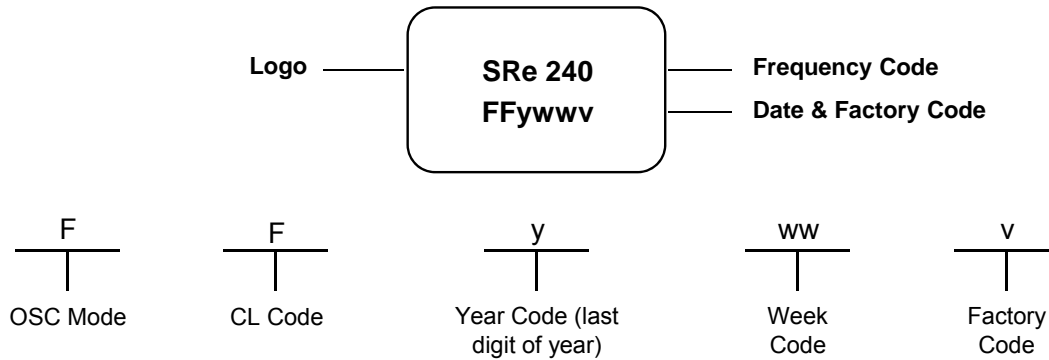
For soldering reflow profile and reliability test ratings go to: <http://www.pericom.com/pdf/sre/reflow.pdf>

TYPE F9 5.0x3.2 GLASS SEALED CRYSTAL

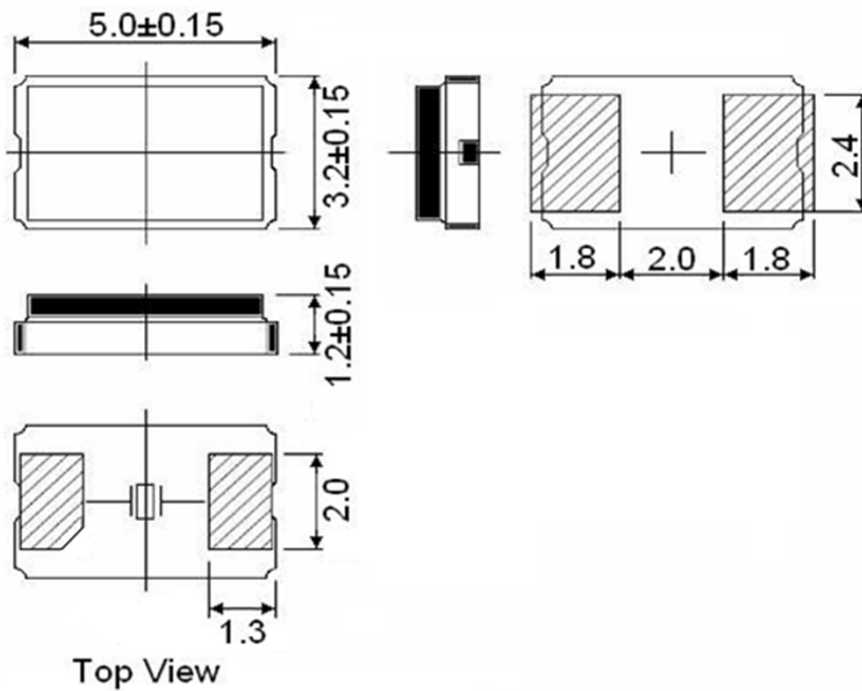
F92400054

VER. C 23-Aug-13

MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)



Note:

Pin shape is only for reference, and the Pin with chamfer or without chamfer is based on the real product.

TYPE F9 5.0x3.2 GLASS SEALED CRYSTAL

F92400054

VER. C 23-Aug-13

PACKING

